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(12) **United States Design Patent** (10) **Patent No.:** **US D938,925 S**
Okawa et al. (45) **Date of Patent:** **** Dec. 21, 2021**

(54) **SEMICONDUCTOR DEVICE**

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(**) Term: **15 Years**

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(52) **U.S. Cl.**
USPC **D13/182**

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CPC H01L 21/00; H01L 21/02; H01L 21/4814; H01L 21/4846; H01L 21/4871; H01L 21/67144; H01L 2224/42; H01L 2224/43; H01L 2224/01; H01L 2224/08055; H01L 2224/08054; H01L 23/12; H01L 23/13; H01L 23/14; H01L 23/147; H01L 23/00; H01L 23/48; H01L 23/4926; H01L 23/495; H01L 23/49517; H01L 23/498; H01L 23/49805; H01L 23/49811; H01L 23/49861; H01L 23/49866; H01L 23/49872; H01L 23/49575; H01L 23/49579; H01L 2924/171; H01L 2924/1711; H01L 2924/1715; H01L 2924/181; H01L 2924/1811; H01L 2924/1815; H01L 2924/19042; H01L 2924/1905

See application file for complete search history.

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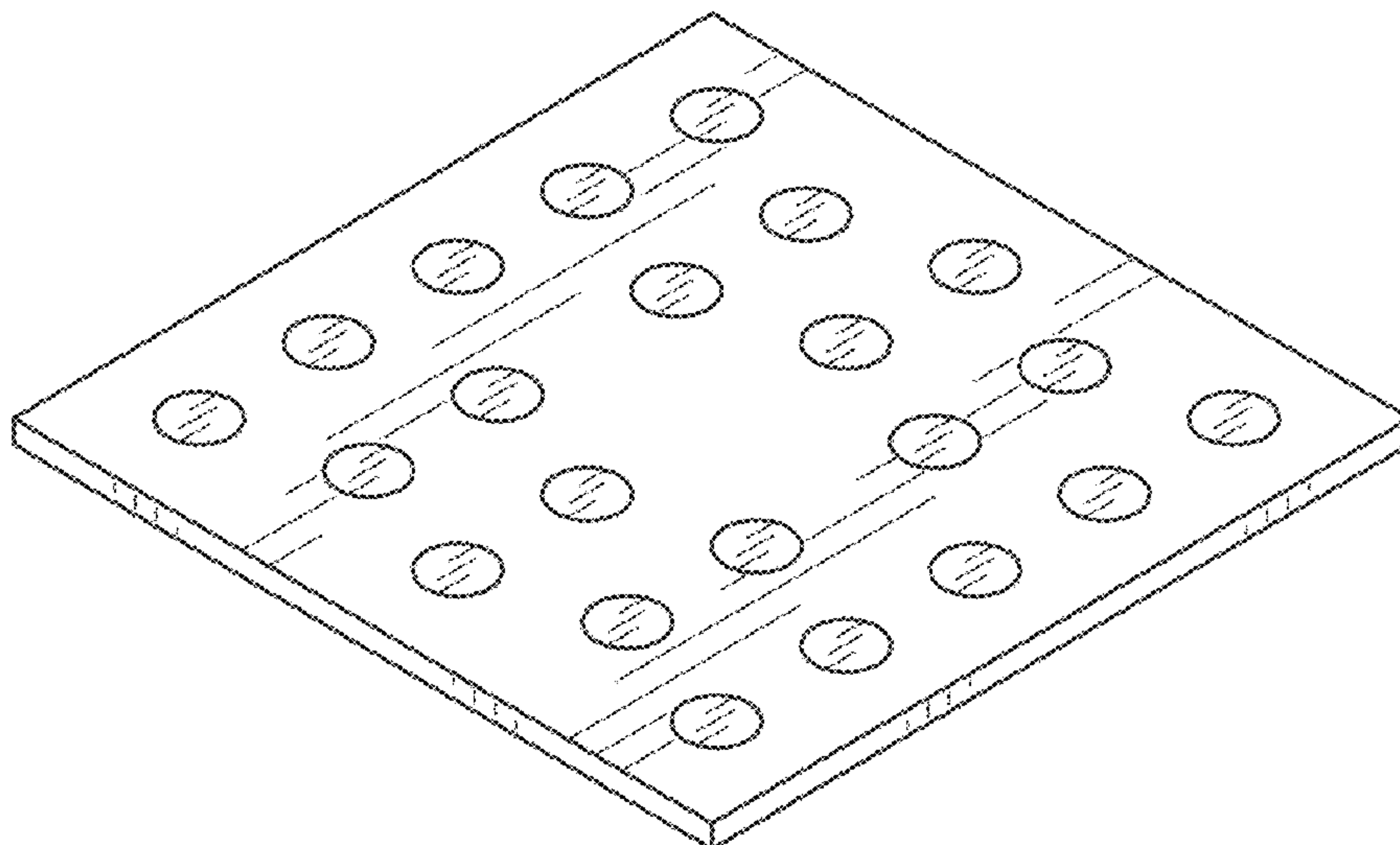
(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a semiconductor device showing our new design;
 FIG. 2 is a front view thereof;
 FIG. 3 is a rear view thereof;
 FIG. 4 is a left side view thereof;
 FIG. 5 is a right side view thereof;
 FIG. 6 is a top plan view thereof; and,
 FIG. 7 is a bottom plan view thereof.

1 Claim, 4 Drawing Sheets



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FIG. 1

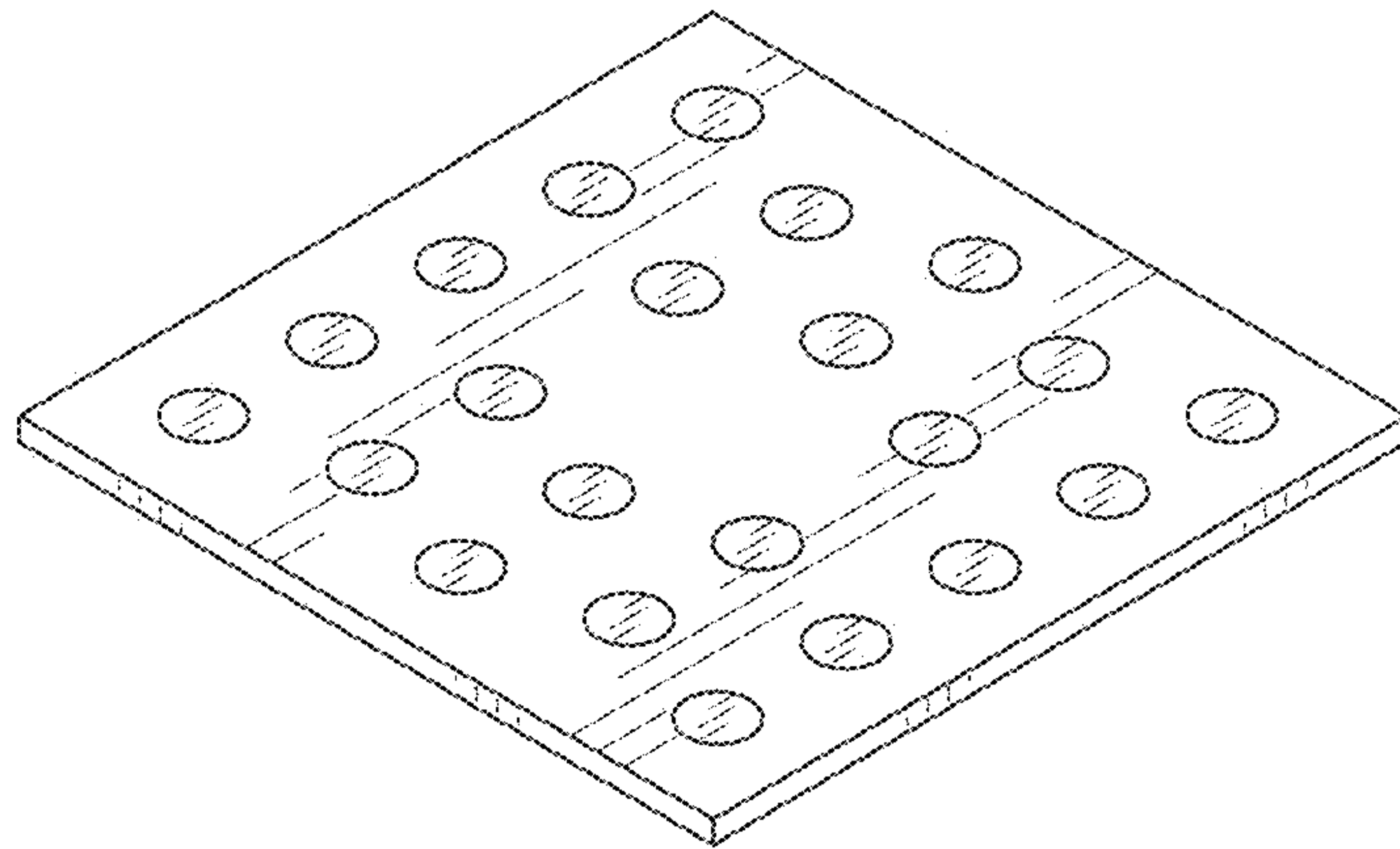


FIG. 2

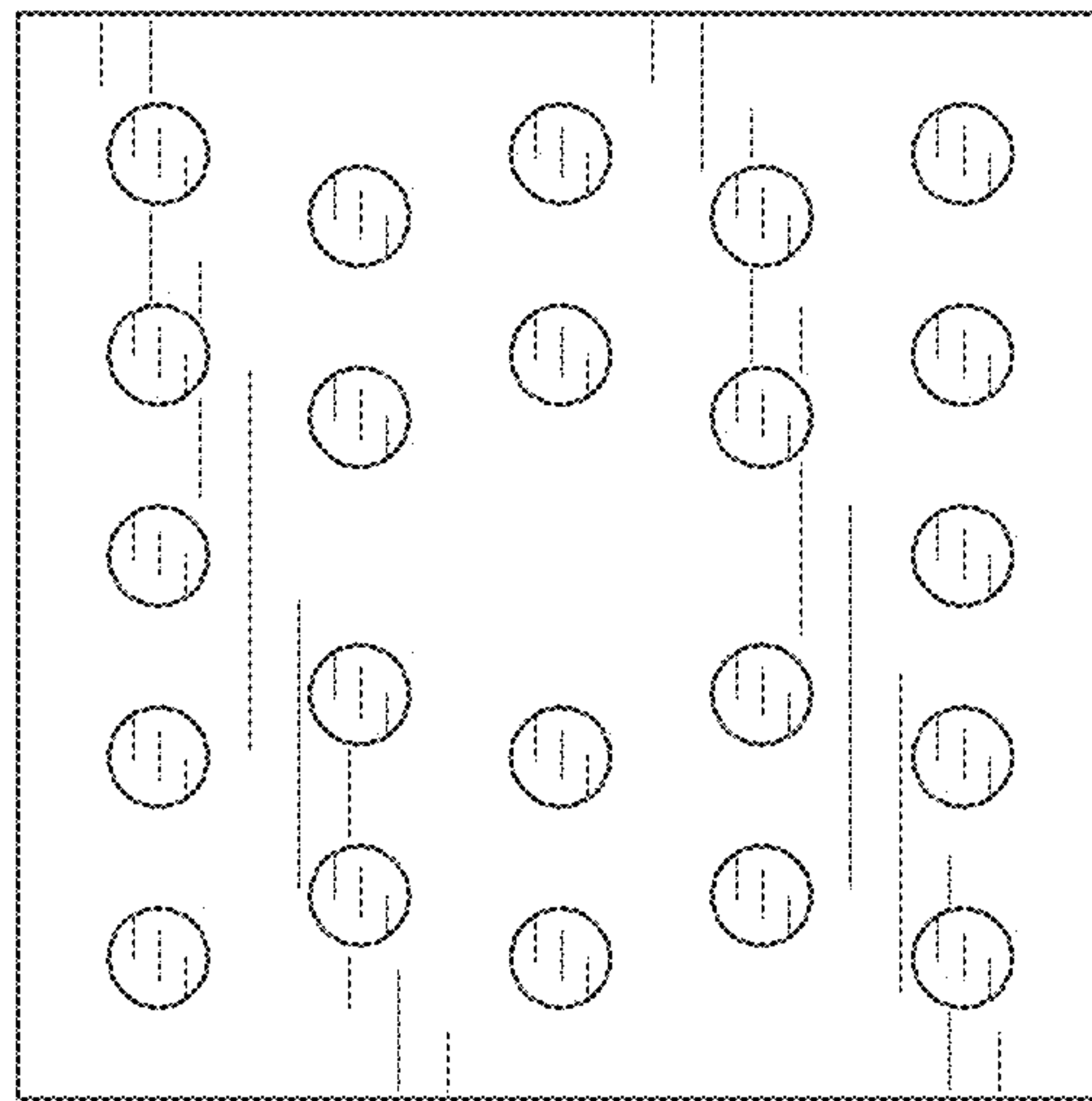


FIG. 3

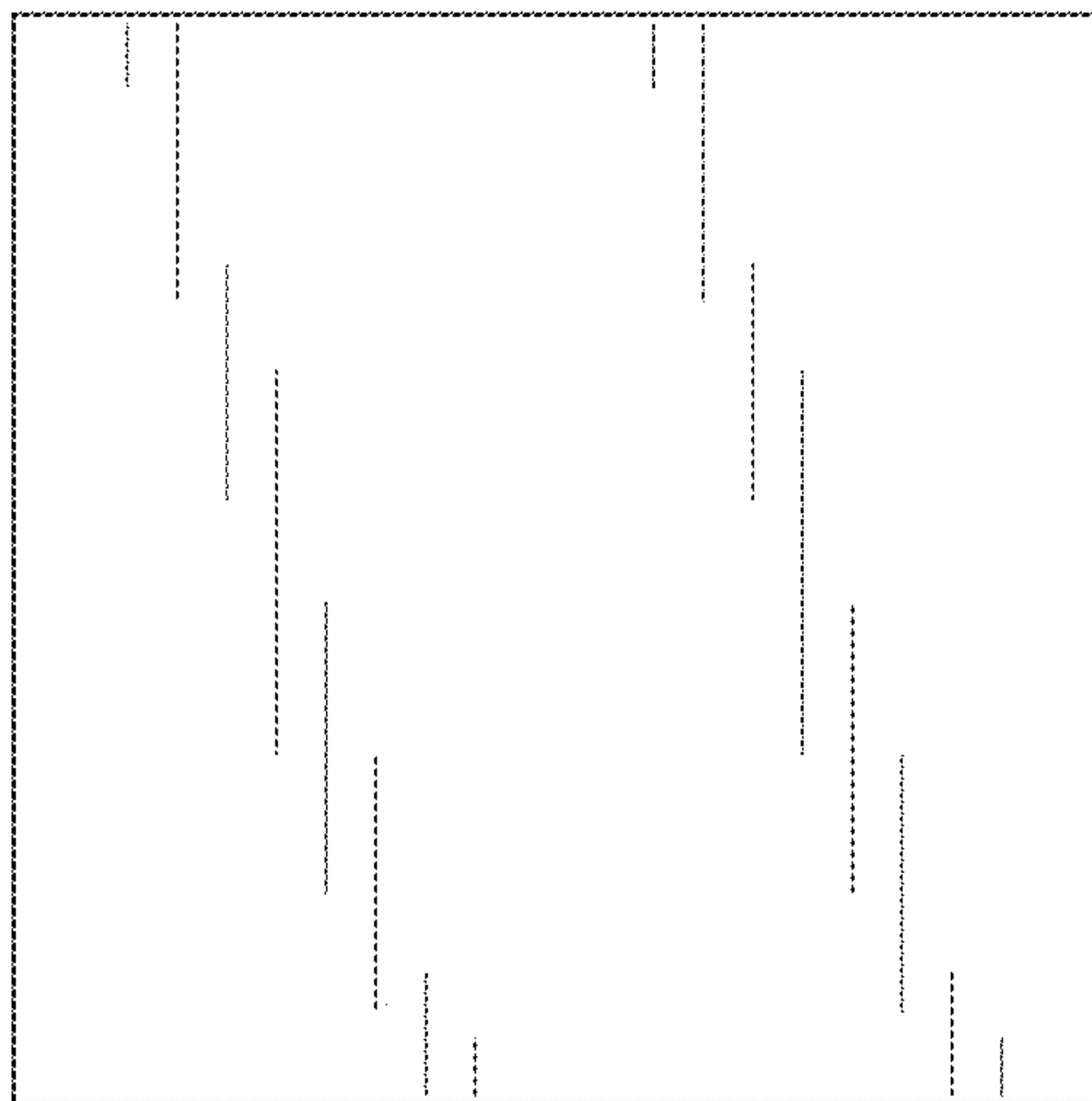


FIG. 4

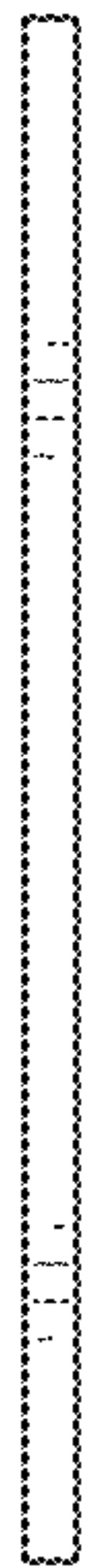


FIG. 5



FIG. 6

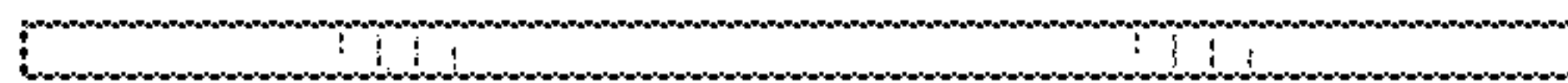


FIG. 7

